ABSTRACT OF THE DISCLOSURE

METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER

In order to form bumps easily on bonding pads with uniform bump head height in case of manufacturing a semiconductor wafer to form bumps thereon by wire bonding, a method for manufacturing a semiconductor wafer comprises the steps of forming bumps on bonding pads formed on a surface of a semiconductor wafer by wire bonding, forming a resin layer by coating a resin on the surface in a manner of burying the bumps, and surfacing the bumps by grinding the resin layer and making the bump head height uniform.

Figure 6.